5 é / Descriptions

TO-263 .> / Ñ?ú 3 « | • 'ož N-CHANNEL MOSFET in a TO-263 Plastic Package.

¤ ª / Features

V_{DS}=100V I_D=65A

$R_{DS(ON)}$@10V 0 10m (Typ.9m)

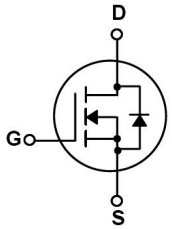
$R_{DS(ON)}$@4.5V 0 15m (Typ.11m)

—)í D }ož HF Product.

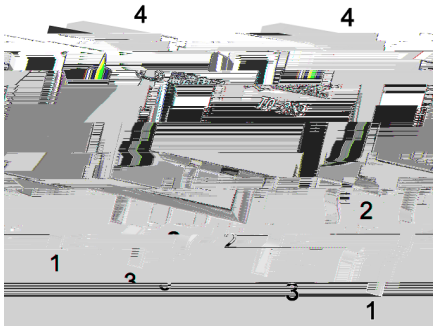
Ð ÷ / Applications

¥ ˜ ^ 9 ä | › % ² k " 6 ,) è y Âf9d'' ÈÈ ÿ ° Ž correction, electronic lamp ballast based on half bridge topology.

Ã W] Ô · / Equivalent Circuit



• Û - æ / Pinning



PIN1 y G PIN 2o•4 y D PIN 3 y S

, M V / Marking

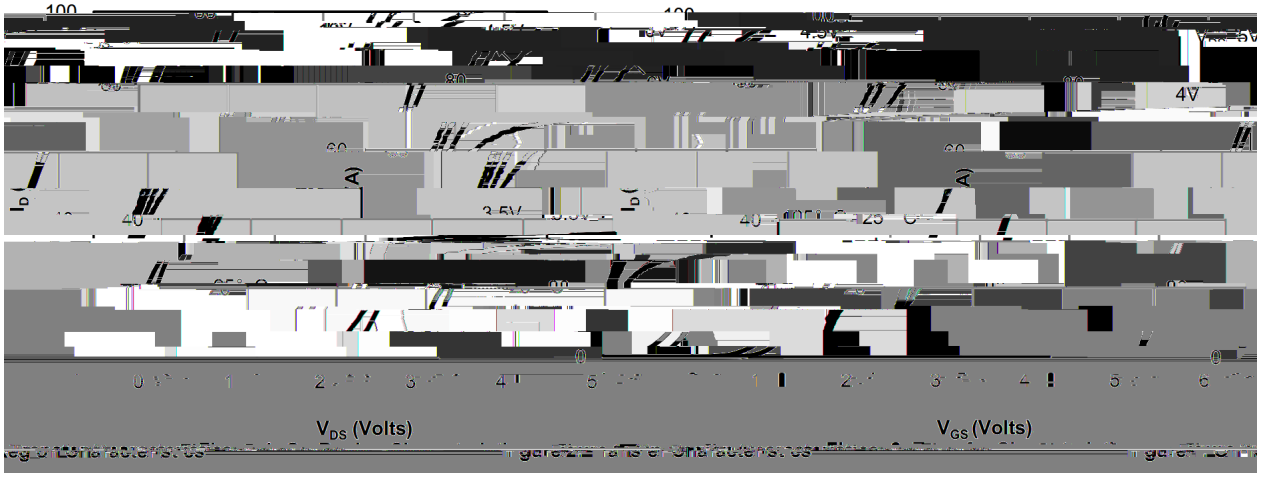
• - ~ ª ¢ož

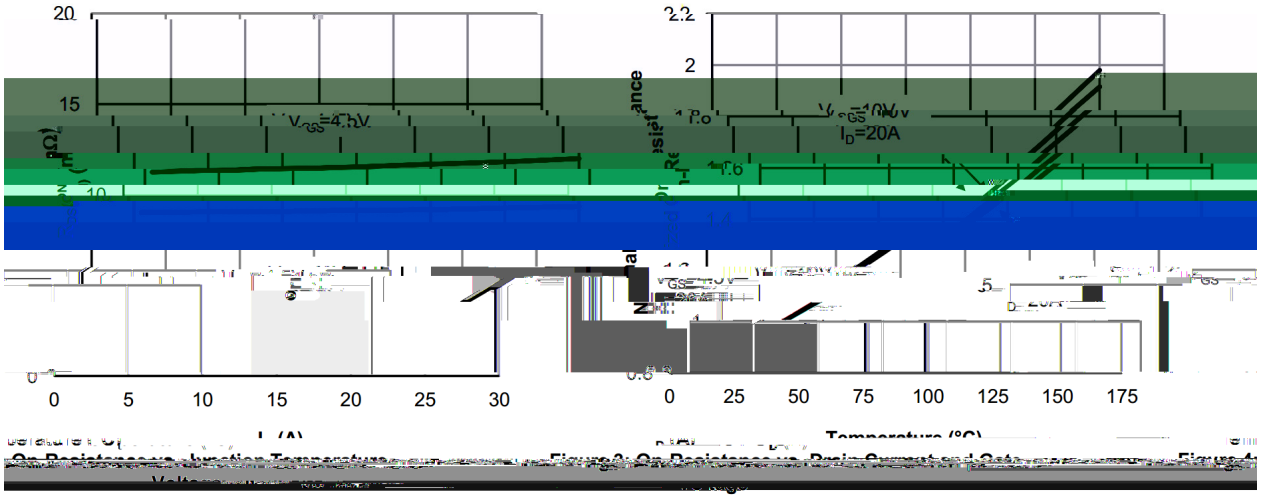
See Marking Instructions.

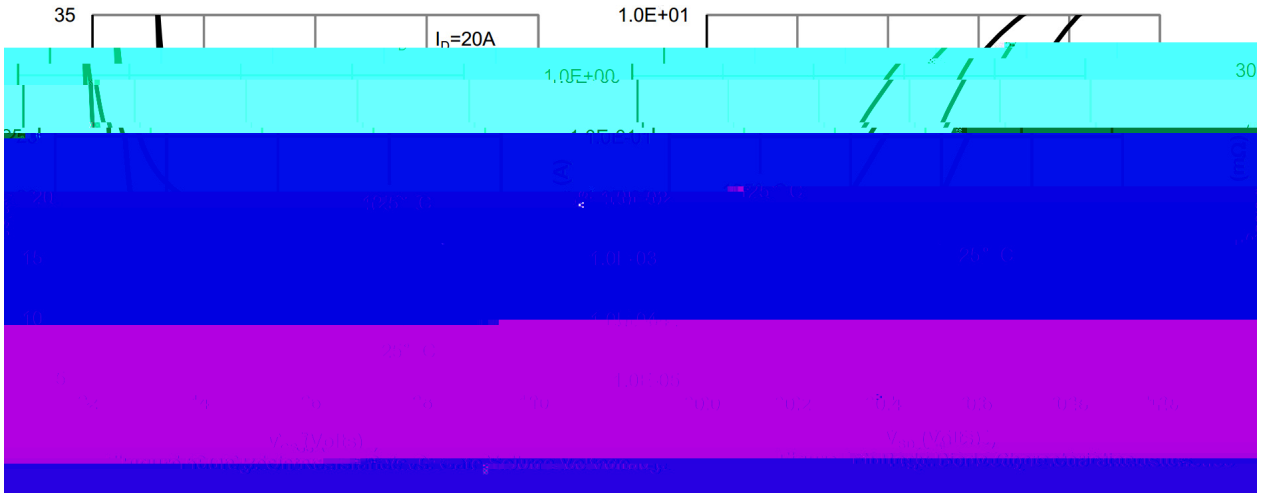
@ *f* Parameter	… Z Symbol	*f* › Rating	% y Unit
Drain-Source Voltage	V_{DSS}	100	V
Drain Current	I_D(Tc=25)	65	A
Pulsed Drain Current	I_{DM}	168	A
Gate-Source Voltage	V_{GS}	f 20	V

@ ƒ Parameter	… Z Symbol	y ¡ Ú ^ Test Conditions	Â 4 › Min	Á º › Typ	Â Ý › Max	% y Unit
Turn-On Delay Time	$t_{d(on)}$	V_{GS}=10V V_{DS}=50V R_L=2.5 R_{GEN}=3		8.7		ns
Turn-On Rise Time	t_r			3.5		
Turn-Off Delay Time	$t_{d(off)}$			25		
Turn-Off Fall Time						

Ô ? d • Ž ¢ / Electrical Characteristic Curve







Ô ? d • Ž ¢ / Electrical Characteristic Curve

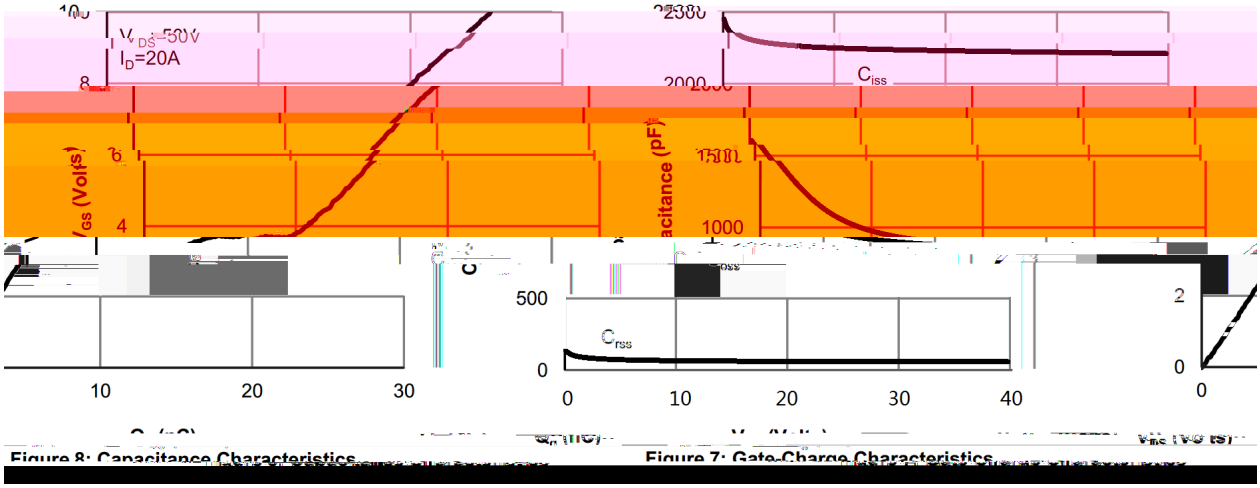


Figure 8: Capacitance Characteristics

Figure 7: Gate-Charge Characteristics

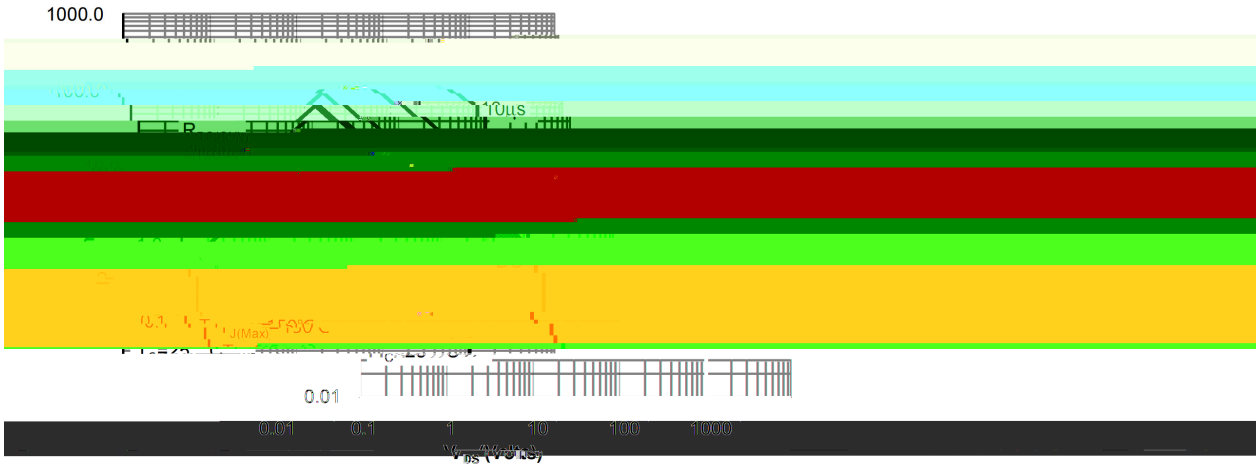


Figure 9: Maximum Forward Biased Safe
Operating Area

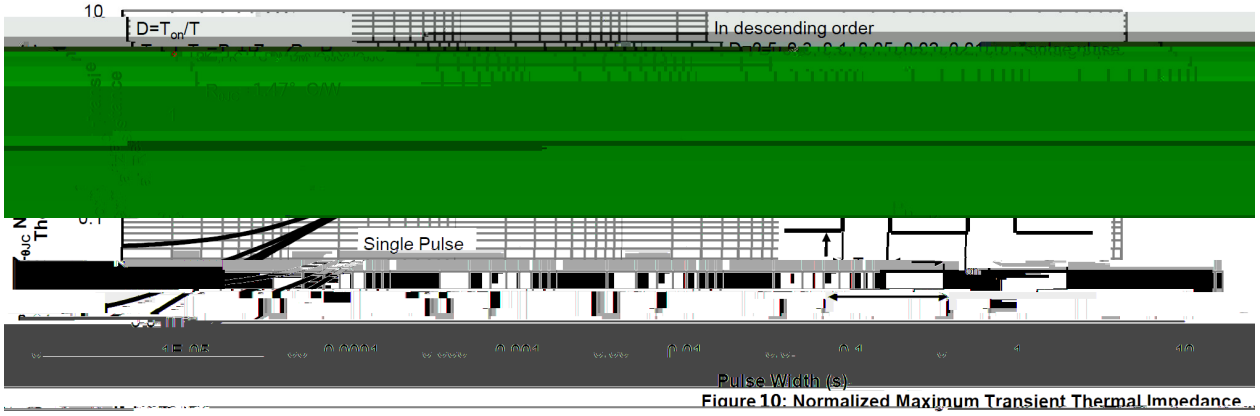
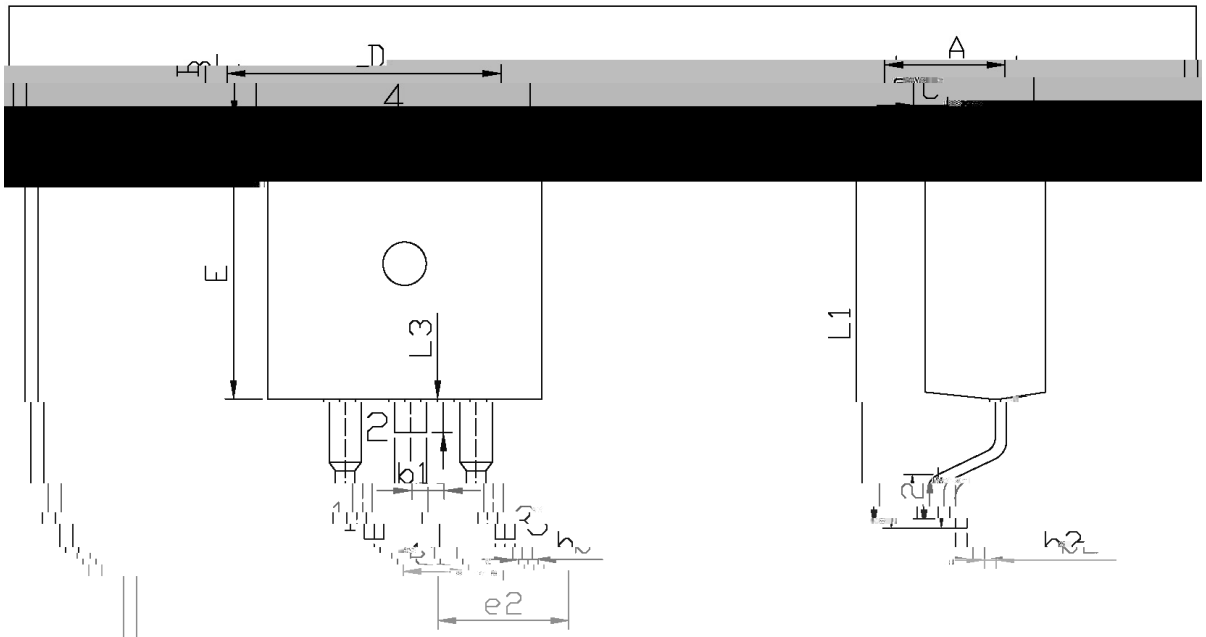


Figure 10: Normalized Maximum Transient Thermal Impedance

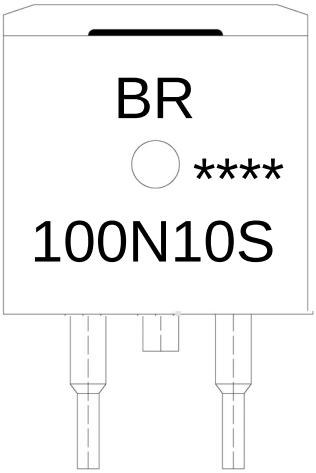
Ø ¤ =) ¢ / Package Dimensions



单位：mm

Dimensions In Millimeters			Dimensions In Millimeters		
Symbol	Min	Max	Symbol	Min	Max
A	4.30	4.70	E	9.00	9.40
B	1.00	1.40	e1	2.34	2.74
b	0.70	0.90	c	0.45	0.60
b1	1.15	1.35	L1	15.00	16.00

, M y ƒ / Marking Instructions



ª ¢ y

(8 y ¸ [W A

4 9 y º Z W A

y ÿ D Z W A k š ÿ D Z J

Note:

BR:	Company Code
100N10S:	Product Type Code
****:	Lot No. Code, code change with Lot No

š WD t … • Ž ¢ (x /) / : K S V K X G Z [X K 6 X U L O R K L U X / 8 8 K L R U] 9 U R J K X O T M 6

ª ¢ y

1o• Ä ½ “ † 150 ½180 - k ž • 60 ½90sec;

2o• Q › “ † 245 r 5 - k ž • 4 Ò 5 r 0.5sec;

3o•D N ò i Ò 0 , † 2 ½10 - /sec.

Note:

1.Preheating:150~180 - , Time:60~90sec.

2.Peak Temp.:245 r 5 - , Duration:5 r 0.5sec.

3. Cooling Speed: 2~10 - /sec.

ÂD /Cã p ¯ »] / Resistance to Soldering Heat Test Conditions

605 r 5 - (/ -5.7(Pack ag 3(g)-5.2286(SBRC5 (Ojtle)-4.3/1 Tox 03.4485 32.3713 TD .0004 Tc -35.6 5309:602
/ / 1ç